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Product Summary

$V_{(BR)DSS}$	$R_{DS(ON) \max}$	$I_D \max$ $T_A = +25^\circ\text{C}$
60V	7.5Ω @ $V_{GS} = 5\text{V}$	0.23A

Description

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

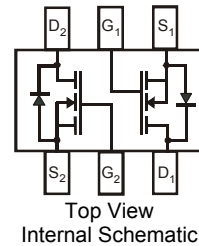
- Motor Control
- Power Management Functions

Features

- Dual N-Channel MOSFET
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Notes 3 & 4)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 ^(e3)
- Terminal Connections: See Diagram
- Weight: 0.006 grams (approximate)

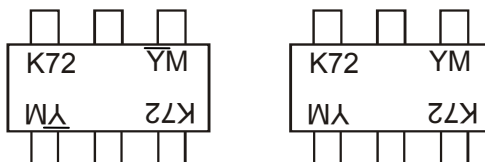


Ordering Information (Note 5)

Part Number	Compliance	Case	Packaging
2N7002DW-7-F	Standard	SOT363	3,000/Tape & Reel
2N7002DWQ-7-F	Automotive	SOT363	3,000/Tape & Reel
2N7002DW-13-F	Standard	SOT363	10,000/Tape & Reel
2N7002DWQ-13-F	Automotive	SOT363	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb_2O_3 Fire Retardants.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



K72 = Product Type Marking Code
 YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)
 ȲM = Date Code Marking for CAT (Chengdu Assembly/ Test site)
 Y or Ȳ = Year (ex: A = 2013)
 M = Month (ex: 9 = September)

Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	...	2011	2012	2013	2014	2015	2016	2017
Code	J	K	L	M	N	P	R	...	Y	Z	A	B	C	D	E

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	60	V
Drain-Gate Voltage $R_{GS} \leq 1.0\text{M}\Omega$	V_{DGR}	60	V
Gate-Source Voltage	Continuous	V_{GSS}	± 20 V
	Pulsed	V_{GSS}	± 40 V
Continuous Drain Current (Note 7) $V_{GS} = 5\text{V}$	Steady State	$T_A = +25^\circ\text{C}$	0.23
		$T_A = +70^\circ\text{C}$	0.18
		$T_A = +100^\circ\text{C}$	0.14
Maximum Continuous Body Diode Forward Current (Note 7)	I_S	0.53	A
Pulsed Drain Current (10 μs pulse, duty cycle = 1%)	I_{DM}	0.8	A

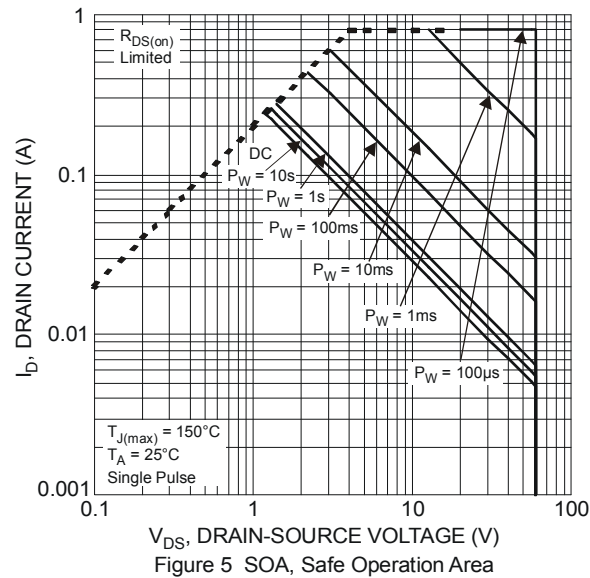
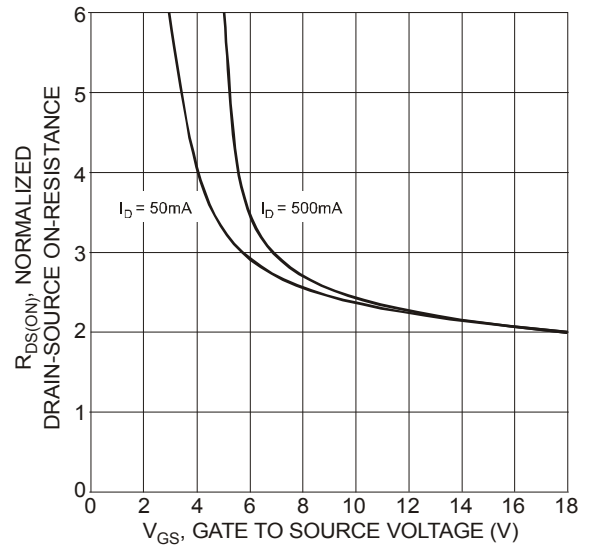
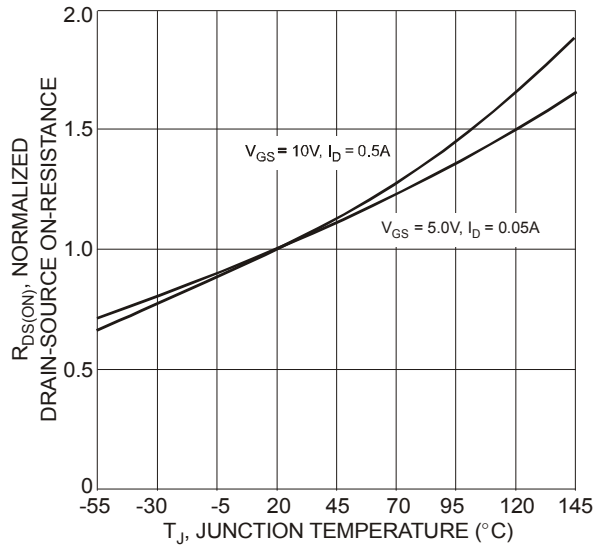
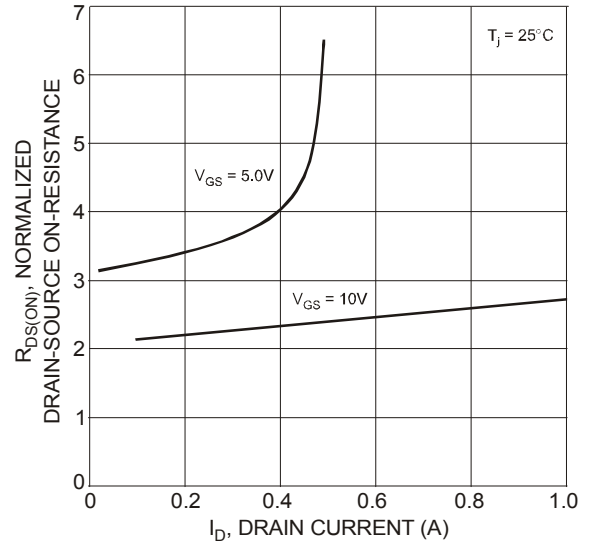
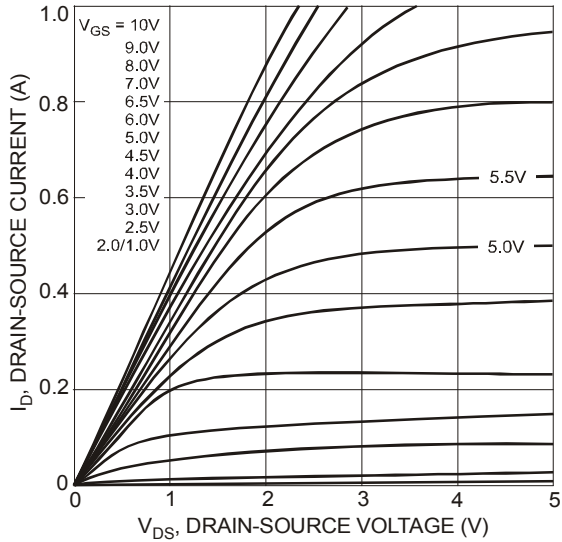
Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 6)	P_D	$T_A = +25^\circ\text{C}$	0.31
		$T_A = +70^\circ\text{C}$	0.2
		$T_A = +100^\circ\text{C}$	0.12
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	$R_{\theta JA}$	410 $^\circ\text{C/W}$
Total Power Dissipation (Note 7)	P_D	$T_A = +25^\circ\text{C}$	0.4
		$T_A = +70^\circ\text{C}$	0.25
		$T_A = +100^\circ\text{C}$	0.15
Thermal Resistance, Junction to Ambient (Note 7)	Steady state	$R_{\theta JA}$	318 $^\circ\text{C/W}$
Thermal Resistance, Junction to Case (Note 7)	Steady state	$R_{\theta JC}$	135 $^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

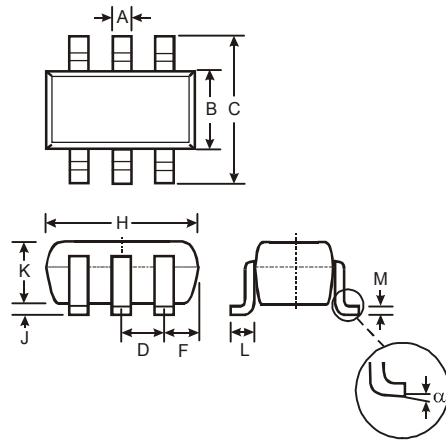
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV_{DSS}	60	70	—	V	$V_{GS} = 0\text{V}, I_D = 10\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1.0 500	μA	$V_{DS} = 60\text{V}, V_{GS} = 0\text{V}$ @ $T_C = +25^\circ\text{C}$ @ $T_C = +125^\circ\text{C}$
Gate-Body Leakage	I_{GSS}	—	—	± 10	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(th)}$	1.0	—	2.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(on)}$	—	3.2 4.4	7.5 13.5	Ω	$V_{GS} = 5.0\text{V}, I_D = 0.05\text{A}$ $V_{GS} = 10\text{V}, I_D = 0.5\text{A}$
		@ $T_J = +25^\circ\text{C}$ @ $T_J = +125^\circ\text{C}$				
On-State Drain Current	$I_{D(on)}$	0.5	1.0	—	A	$V_{GS} = 10\text{V}, V_{DS} = 7.5\text{V}$
Forward Transconductance	g_{FS}	80	—	—	mS	$V_{DS} = 10\text{V}, I_D = 0.2\text{A}$
Diode Forward Voltage	V_{SD}	—	0.78	1.5	V	$V_{GS} = 0\text{V}, I_S = 115\text{mA}$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	—	22	50	pF	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}$ $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	11	25	pF	
Reverse Transfer Capacitance	C_{rss}	—	2.0	5.0	pF	
SWITCHING CHARACTERISTICS (Note 9)						
Turn-On Delay Time	$t_{D(on)}$	—	7.0	20	ns	$V_{DD} = 30\text{V}, I_D = 0.2\text{A},$ $R_L = 150\Omega, V_{GEN} = 10\text{V},$ $R_{GEN} = 25\Omega$
Turn-Off Delay Time	$t_{D(off)}$	—	11.0	20		

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.



Package Outline Dimensions

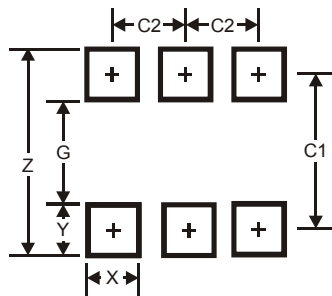
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

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